Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

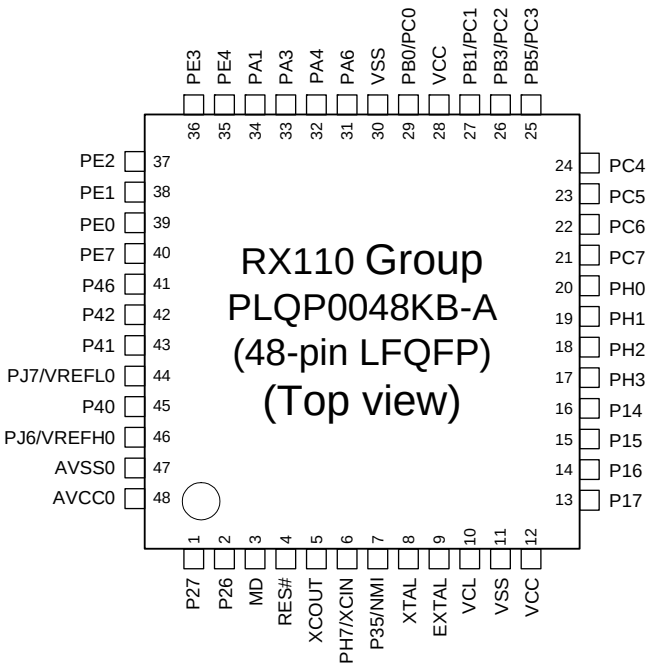
Applications of "Embedded - Microcontrollers"

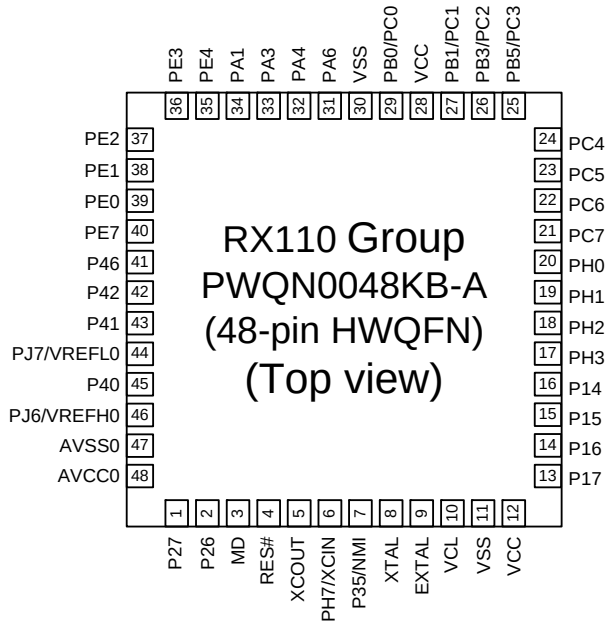
Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51105adfk-30

Table 1.3 List of Products (2/2)

Group	Part No.	Orderable Part No.	Package	ROM Capacity	RAM Capacity	Maximum Operating Frequency	Operating Temperature
RX110	R5F51105ADFM	R5F51105ADFM#30	PLQP0064KB-A	128 Kbytes	16 Kbytes	32MHz	–40 to +85°C
	R5F51105ADFK	R5F51105ADFK#30	PLQP0064GA-A				
	R5F51105ADLF	R5F51105ADLF#U0	PWLG0064KA-A				
	R5F51105ADFL	R5F51105ADFL#30	PLQP0048KB-A				
	R5F51105ADNE	R5F51105ADNE#U0	PWQN0048KB-A				
	R5F51104ADFM	R5F51104ADFM#30	PLQP0064KB-A	96 Kbytes			
	R5F51104ADFK	R5F51104ADFK#30	PLQP0064GA-A				
	R5F51104ADLF	R5F51104ADLF#U0	PWLG0064KA-A				
	R5F51104ADFL	R5F51104ADFL#30	PLQP0048KB-A				
	R5F51104ADNE	R5F51104ADNE#U0	PWQN0048KB-A				
	R5F51103ADFM	R5F51103ADFM#30	PLQP0064KB-A	64 Kbytes	10 Kbytes		
	R5F51103ADFK	R5F51103ADFK#30	PLQP0064GA-A				
	R5F51103ADLF	R5F51103ADLF#U0	PWLG0064KA-A				
	R5F51103ADFL	R5F51103ADFL#30	PLQP0048KB-A				
	R5F51103ADNE	R5F51103ADNE#U0	PWQN0048KB-A				
	R5F51103ADLM	R5F51103ADLM#U0	PWLG0036KA-A				
	R5F51103ADNF	R5F51103ADNF#U0	PWQN0040KC-A				
	R5F51101ADFM	R5F51101ADFM#30	PLQP0064KB-A	32 Kbytes			
	R5F51101ADFK	R5F51101ADFK#30	PLQP0064GA-A				
	R5F51101ADLF	R5F51101ADLF#U0	PWLG0064KA-A				
	R5F51101ADFL	R5F51101ADFL#30	PLQP0048KB-A				
	R5F51101ADNE	R5F51101ADNE#U0	PWQN0048KB-A				
	R5F51101ADLM	R5F51101ADLM#U0	PWLG0036KA-A				
	R5F51101ADNF	R5F51101ADNF#U0	PWQN0040KC-A				
	R5F5110JADFM	R5F5110JADFM#30	PLQP0064KB-A	16 Kbytes	8 Kbytes		
	R5F5110JADFK	R5F5110JADFK#30	PLQP0064GA-A				
	R5F5110JADLF	R5F5110JADLF#U0	PWLG0064KA-A				
	R5F5110JADFL	R5F5110JADFL#30	PLQP0048KB-A				
	R5F5110JADNE	R5F5110JADNE#U0	PWQN0048KB-A				
	R5F5110JADLM	R5F5110JADLM#U0	PWLG0036KA-A				
	R5F5110JADNF	R5F5110JADNF#U0	PWQN0040KC-A				
	R5F5110HADLM	R5F5110HADLM#U0	PWLG0036KA-A	8 Kbytes			
	R5F5110HADNF	R5F5110HADNF#U0	PWQN0040KC-A				

Note: Orderable part numbers are current as of when this manual was published. Please make sure to refer to the relevant product page on the Renesas website for the latest part numbers.

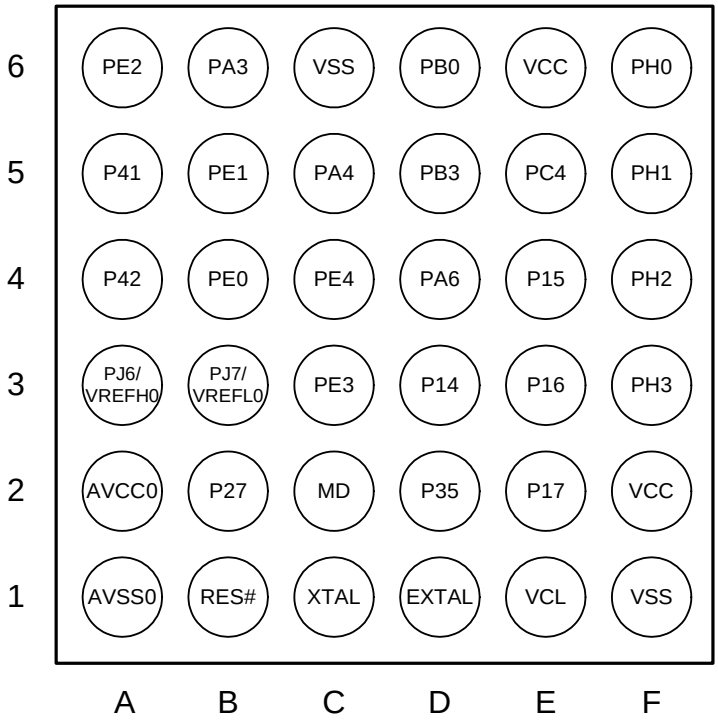




Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (48-Pin LFQFP/HWQFN)”.
Note: It is recommended that the exposed die pad of HWQFN should be connected to VSS.

Figure 1.5 Pin Assignments of the 48-Pin LFQFP/HWQFN

RX110 Group
PWLG0036KA-A
(36-pin WFLGA)
(Upper perspective view)



Note: This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (36-Pin WFLGA)”.
Note: For the position of A1 pin in the package, see “Package Dimensions”.

Figure 1.7 Pin Assignments of the 36-Pin WFLGA

2.1 General-Purpose Registers (R0 to R15)

This CPU has 16 general-purpose registers (R0 to R15). R0 to R15 can be used as data registers or address registers. R0, a general-purpose register, also functions as the stack pointer (SP). The stack pointer is switched to operate as the interrupt stack pointer (ISP) or user stack pointer (USP) by the value of the stack pointer select bit (U) in the processor status word (PSW).

2.2 Control Registers

(1) Interrupt Stack Pointer (ISP)/User Stack Pointer (USP)

The stack pointer (SP) can be either of two types, the interrupt stack pointer (ISP) or the user stack pointer (USP). Whether the stack pointer operates as the ISP or USP depends on the value of the stack pointer select bit (U) in the processor status word (PSW).
Set the ISP or USP to a multiple of 4, as this reduces the numbers of cycles required to execute interrupt sequences and instructions entailing stack manipulation.

(2) Interrupt Table Register (INTB)

The interrupt table register (INTB) specifies the address where the relocatable vector table starts.

(3) Program Counter (PC)

The program counter (PC) indicates the address of the instruction being executed.

(4) Processor Status Word (PSW)

The processor status word (PSW) indicates the results of instruction execution or the state of the CPU.

(5) Backup PC (BPC)

The backup PC (BPC) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the program counter (PC) are saved in the BPC register.

(6) Backup PSW (BPSW)

The backup PSW (BPSW) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the processor status word (PSW) are saved in the BPSW. The allocation of bits in the BPSW corresponds to that in the PSW.

(7) Fast Interrupt Vector Register (FINTV)

The fast interrupt vector register (FINTV) is provided to speed up response to interrupts.
The FINTV register specifies a branch destination address when a fast interrupt has been generated.

2.3 Register Associated with DSP Instructions

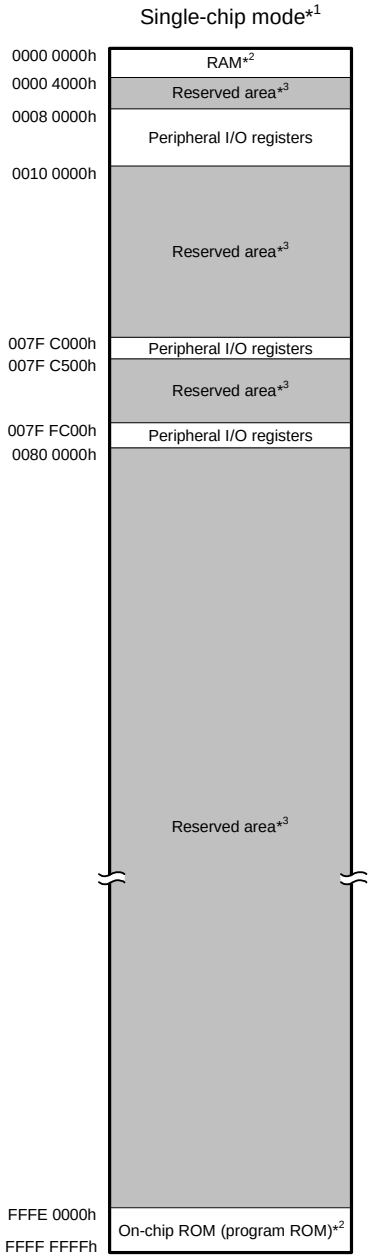
(1) Accumulator (ACC)

The accumulator (ACC) is a 64-bit register used for DSP instructions. The accumulator is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, MUL, and RMPA, in which case the prior value in the accumulator is modified by execution of the instruction.
Use the MVTACHI and MVTACLO instructions for writing to the accumulator. The MVTACHI and MVTACLO instructions write data to the higher-order 32 bits (bits 63 to 32) and the lower-order 32 bits (bits 31 to 0), respectively.
Use the MVFACHI and MVFACMI instructions for reading data from the accumulator. The MVFACHI and MVFACMI instructions read data from the higher-order 32 bits (bits 63 to 32) and the middle 32 bits (bits 47 to 16), respectively.

3. Address Space

3.1 Address Space

This MCU has a 4-Gbyte address space, consisting of the range of addresses from 0000 0000h to FFFF FFFFh. That is, linear access to an address space of up to 4 Gbytes is possible, and this contains program area.
Figure 3.1 shows the memory map.



Note 1. The address space in boot mode is the same as the address space in single-chip mode.
Note 2. The capacity of ROM/RAM differs depending on the products.

ROM (bytes)		RAM (bytes)	
Capacity	**Address**	**Capacity**	**Address**
128 K	FFFE 0000h to FFFF FFFFh	16 K	0000 0000h to 0000 3FFFh
96 K	FFFE 8000h to FFFF FFFFh		
64 K	FFFF 0000h to FFFF FFFFh	10 K	0000 0000h to 0000 27FFh
32 K	FFFF 8000h to FFFF FFFFh		
16 K	FFFF C000h to FFFF FFFFh	8 K	0000 0000h to 0000 1FFFh
8 K	FFFF E000h to FFFF FFFFh		

Note:See Table 1.3, List of Products, for the product type name.

Note 3. Reserved areas should not be accessed.

Figure 3.1 Memory Map

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to I/O registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

While writing to an I/O register, the CPU starts executing subsequent instructions before the I/O register write access is completed. This may cause the subsequent instructions to be executed before the write value is reflected in the operation. The examples below show how subsequent instructions must be executed after a write access to an I/O register is completed.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) set to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

(a) Write to an I/O register.
(b) Read the value in the I/O register and write it to a general register.
(c) Execute the operation using the value read.
(d) Execute the subsequent instruction.

Example of instructions

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

Table 4.1 List of I/O Registers (Address Order) (4/13)

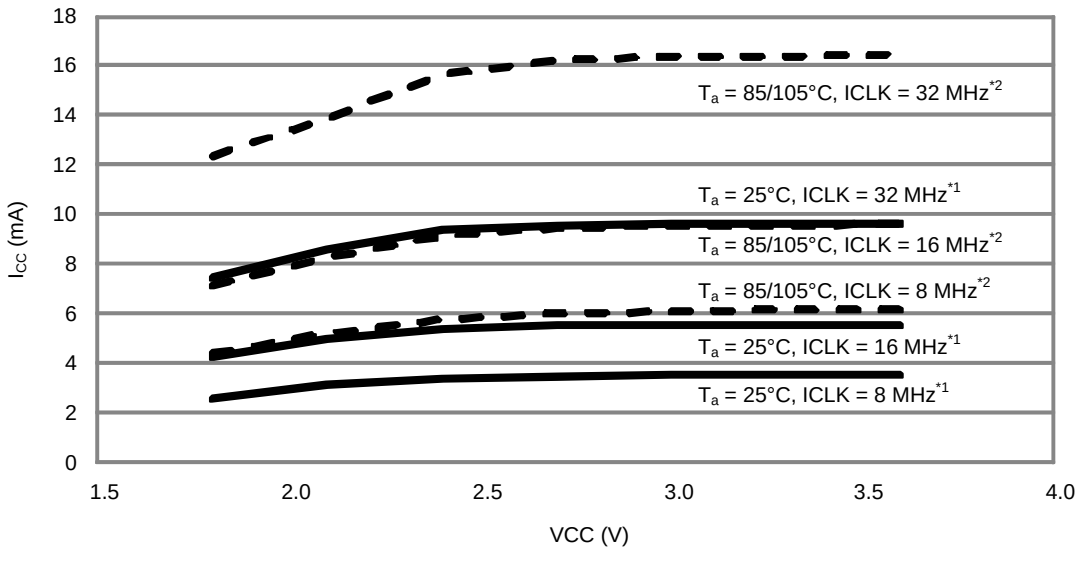
Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 71F8h	ICU	DTC Activation Enable Register 248	DTCER248	8	8	2 ICLK
0008 7202h	ICU	Interrupt Request Enable Register 02	IER02	8	8	2 ICLK
0008 7203h	ICU	Interrupt Request Enable Register 03	IER03	8	8	2 ICLK
0008 7204h	ICU	Interrupt Request Enable Register 04	IER04	8	8	2 ICLK
0008 7205h	ICU	Interrupt Request Enable Register 05	IER05	8	8	2 ICLK
0008 7207h	ICU	Interrupt Request Enable Register 07	IER07	8	8	2 ICLK
0008 7208h	ICU	Interrupt Request Enable Register 08	IER08	8	8	2 ICLK
0008 720Bh	ICU	Interrupt Request Enable Register 0B	IER0B	8	8	2 ICLK
0008 720Ch	ICU	Interrupt Request Enable Register 0C	IER0C	8	8	2 ICLK
0008 720Eh	ICU	Interrupt Request Enable Register 0E	IER0E	8	8	2 ICLK
0008 720Fh	ICU	Interrupt Request Enable Register 0F	IER0F	8	8	2 ICLK
0008 7210h	ICU	Interrupt Request Enable Register 10	IER10	8	8	2 ICLK
0008 7211h	ICU	Interrupt Request Enable Register 11	IER11	8	8	2 ICLK
0008 721Bh	ICU	Interrupt Request Enable Register 1B	IER1B	8	8	2 ICLK
0008 721Ch	ICU	Interrupt Request Enable Register 1C	IER1C	8	8	2 ICLK
0008 721Dh	ICU	Interrupt Request Enable Register 1D	IER1D	8	8	2 ICLK
0008 721Eh	ICU	Interrupt Request Enable Register 1E	IER1E	8	8	2 ICLK
0008 721Fh	ICU	Interrupt Request Enable Register 1F	IER1F	8	8	2 ICLK
0008 72E0h	ICU	Software Interrupt Activation Register	SWINTR	8	8	2 ICLK
0008 72F0h	ICU	Fast Interrupt Set Register	FIR	16	16	2 ICLK
0008 7300h	ICU	Interrupt Source Priority Register 000	IPR000	8	8	2 ICLK
0008 7303h	ICU	Interrupt Source Priority Register 003	IPR003	8	8	2 ICLK
0008 7304h	ICU	Interrupt Source Priority Register 004	IPR004	8	8	2 ICLK
0008 7305h	ICU	Interrupt Source Priority Register 005	IPR005	8	8	2 ICLK
0008 7320h	ICU	Interrupt Source Priority Register 032	IPR032	8	8	2 ICLK
0008 7321h	ICU	Interrupt Source Priority Register 033	IPR033	8	8	2 ICLK
0008 7322h	ICU	Interrupt Source Priority Register 034	IPR034	8	8	2 ICLK
0008 732Ch	ICU	Interrupt Source Priority Register 044	IPR044	8	8	2 ICLK
0008 7339h	ICU	Interrupt Source Priority Register 057	IPR057	8	8	2 ICLK
0008 733Fh	ICU	Interrupt Source Priority Register 063	IPR063	8	8	2 ICLK
0008 7340h	ICU	Interrupt Source Priority Register 064	IPR064	8	8	2 ICLK
0008 7341h	ICU	Interrupt Source Priority Register 065	IPR065	8	8	2 ICLK
0008 7342h	ICU	Interrupt Source Priority Register 066	IPR066	8	8	2 ICLK
0008 7343h	ICU	Interrupt Source Priority Register 067	IPR067	8	8	2 ICLK
0008 7344h	ICU	Interrupt Source Priority Register 068	IPR068	8	8	2 ICLK
0008 7345h	ICU	Interrupt Source Priority Register 069	IPR069	8	8	2 ICLK
0008 7346h	ICU	Interrupt Source Priority Register 070	IPR070	8	8	2 ICLK
0008 7347h	ICU	Interrupt Source Priority Register 071	IPR071	8	8	2 ICLK
0008 7358h	ICU	Interrupt Source Priority Register 088	IPR088	8	8	2 ICLK
0008 7359h	ICU	Interrupt Source Priority Register 089	IPR089	8	8	2 ICLK
0008 735Ch	ICU	Interrupt Source Priority Register 092	IPR092	8	8	2 ICLK
0008 735Dh	ICU	Interrupt Source Priority Register 093	IPR093	8	8	2 ICLK
0008 7366h	ICU	Interrupt Source Priority Register 102	IPR102	8	8	2 ICLK
0008 7367h	ICU	Interrupt Source Priority Register 103	IPR103	8	8	2 ICLK
0008 7372h	ICU	Interrupt Source Priority Register 114	IPR114	8	8	2 ICLK
0008 7376h	ICU	Interrupt Source Priority Register 118	IPR118	8	8	2 ICLK
0008 7379h	ICU	Interrupt Source Priority Register 121	IPR121	8	8	2 ICLK
0008 737Bh	ICU	Interrupt Source Priority Register 123	IPR123	8	8	2 ICLK
0008 737Dh	ICU	Interrupt Source Priority Register 125	IPR125	8	8	2 ICLK
0008 737Fh	ICU	Interrupt Source Priority Register 127	IPR127	8	8	2 ICLK
0008 738Bh	ICU	Interrupt Source Priority Register 139	IPR139	8	8	2 ICLK
0008 73DAh	ICU	Interrupt Source Priority Register 218	IPR218	8	8	2 ICLK

Table 5.7 DC Characteristics (5) (2/2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	Low-speed operating mode	Normal operating mode	No peripheral operation*7	ICLK = 32.768 kHz	I_{CC}	3.9	—	µA	
			All peripheral operation: Normal*8, *9	ICLK = 32.768 kHz		10.4	—		
			All peripheral operation: Max.*8, *9	ICLK = 32.768 kHz		—	36		
		Sleep mode	No peripheral operation*7	ICLK = 32.768 kHz		2.1	—		
			All peripheral operation: Normal*8	ICLK = 32.768 kHz		5.6	—		
		Deep sleep mode	No peripheral operation*7	ICLK = 32.768 kHz		1.7	—		
			All peripheral operation: Normal*8	ICLK = 32.768 kHz		3.9	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. Clock supply to the peripheral functions is stopped. The clock source is HOCO. FCLK and PCLK are set to divided by 64.
Note 3. Clocks are supplied to the peripheral functions. The clock source is HOCO. FCLK and PCLK are set to the same frequency as ICLK.
Note 4. Values when VCC = 3.3 V.
Note 5. Clock supply to the peripheral functions is stopped. The clock source is the main oscillation circuit when ICLK = 12 MHz and HOCO when ICLK = 8 or 1 MHz. FCLK and PCLK are set to divided by 64.
Note 6. Clocks are supplied to the peripheral functions. The clock source is the main oscillation circuit when ICLK = 12 MHz and HOCO when ICLK = 8 or 1 MHz. FCLK and PCLK are set to the same frequency as ICLK.
Note 7. Clock supply to the peripheral functions is stopped. The clock source is the sub-clock oscillator. FCLK and PCLK are set to divided by 64.
Note 8. Clocks are supplied to the peripheral functions. The clock source is the sub-clock oscillator. FCLK and PCLK are set to the same frequency as ICLK.
Note 9. Values when the MSTPCRA.MSTPA17 bit (12-bit A/D converter module stop bit) is set to “transition to the module stop state is made”.



Note 1. All peripheral operation is normal. Average value of the tested middle samples during product evaluation
Note 2. All peripheral operation is maximum. Average value of the tested upper-limit samples during product evaluation.

Figure 5.1 Voltage Dependency in High-Speed Operating Mode (Reference Data)

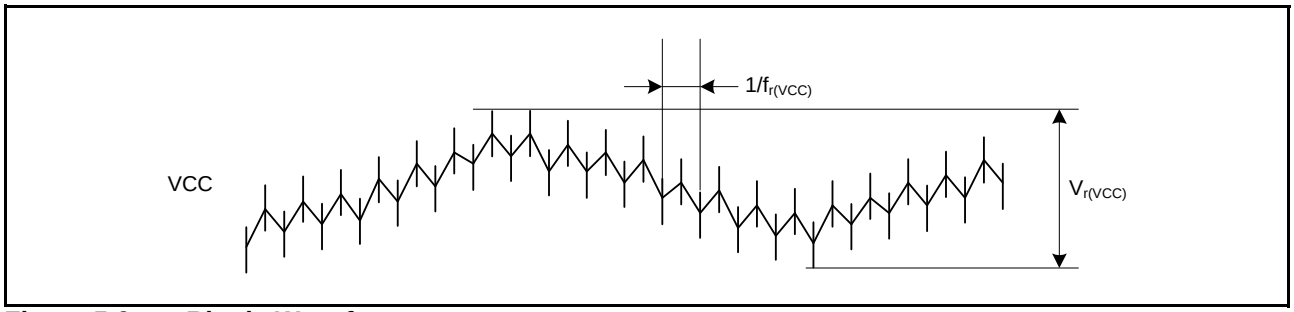


Figure 5.6 Ripple Waveform

Table 5.14 DC Characteristics (12)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Permissible error of VCL pin external capacitance	C_{VCL}	1.4	4.7	7.0	µF	

Note: The recommended capacitance is 4.7 µF. Variations in connected capacitors should be within the above range.

Table 5.15 Permissible Output Currents (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V,
T_a = –40 to +85°C (D version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	2.4	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		30	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		30	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		30	
	Total of all output pins		60	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		–10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		–15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

Table 5.22 Clock Timing

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
XTAL external clock input cycle time		t_{Xcyc}	50	—	—	ns	Figure 5.18
XTAL external clock input high pulse width		t_{XH}	20	—	—	ns	
XTAL external clock input low pulse width		t_{XL}	20	—	—	ns	
XTAL external clock rising time		t_{Xr}	—	—	5	ns	
XTAL external clock falling time		t_{Xf}	—	—	5	ns	
XTAL external clock input wait time*1		t_{EXWT}	0.5	—	—	μs	
Main clock oscillator oscillation frequency	2.4 ≤ VCC ≤ 3.6	f_{MAIN}	1	—	20	MHz	
	1.8 ≤ VCC < 2.4		1	—	8		
Main clock oscillation stabilization time (crystal)*2		$t_{MAINOSC}$	—	3	—	ms	Figure 5.20
Main clock oscillation stabilization time (ceramic resonator)*2		$t_{MAINOSC}$	—	50		μs	
LOCO clock oscillation frequency		f_{LOCO}	3.44	4.0	4.56	MHz	
LOCO clock oscillation stabilization time		t_{LOCO}	—	—	0.5	μs	Figure 5.21
IWDT-dedicated clock oscillation frequency		f_{ILOCO}	12.75	15	17.25	kHz	
IWDT-dedicated clock oscillation stabilization time		t_{ILOCO}	—	—	50	μs	Figure 5.19
HOCO clock oscillation frequency		f_{HOCO}	31.52	32	32.48	MHz	T_a = –40 to 85°C
			31.68	32	32.32		T_a = –20 to 85°C
			31.36	32	32.64		T_a = –40 to 105°C
HOCO clock oscillation stabilization time		t_{HOCO2}	—	—	56	μs	Figure 5.23
Sub-clock oscillator oscillation frequency*4		f_{SUB}	—	32.768	—	kHz	
Sub-clock oscillation stabilization time*3		t_{SUBOSC}	—	0.5	—	s	Figure 5.24

Note 1. Time until the clock can be used after the main clock oscillator stop bit (MOSCCR.MOSTP) is set to 0 (operating) when the external clock is stable.

Note 2. Reference values when an 8-MHz oscillator is used.
When specifying the main clock oscillator stabilization time, set the MOSCWTCR register with a stabilization time value that is equal to or greater than the oscillator-manufacturer-recommended value.
After changing the setting of the MOSCCR.MOSTP bit so that the main clock oscillator operates, read the OSCOVFSR.MOOVF flag to confirm that is has become 1, and then start using the main clock.

Note 3. After changing the setting of the SOSCCR.SOSTP bit or RCR3.RTCEN bit so that the sub-clock oscillator operates, only start using the sub-clock after the sub-clock oscillation stabilization wait time that is equal to or greater than the oscillator-manufacturer-recommended value has elapsed.
Reference value when a 32.768-kHz resonator is used.

Note 4. Only 32.768 kHz can be used.

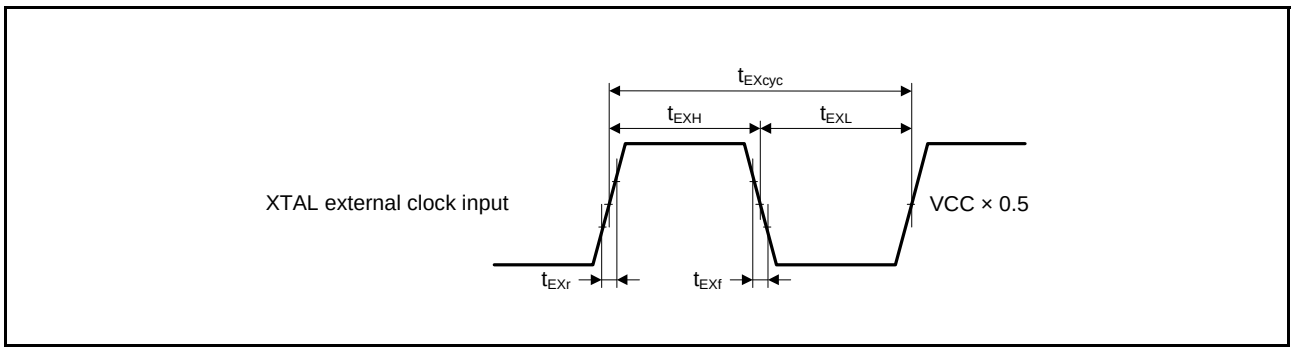


Figure 5.18 XTAL External Clock Input Timing

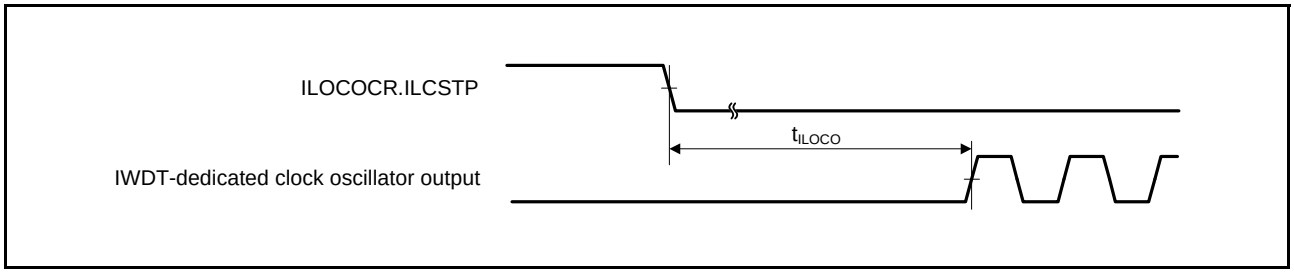


Figure 5.19 IWDT-Dedicated Clock Oscillation Start Timing

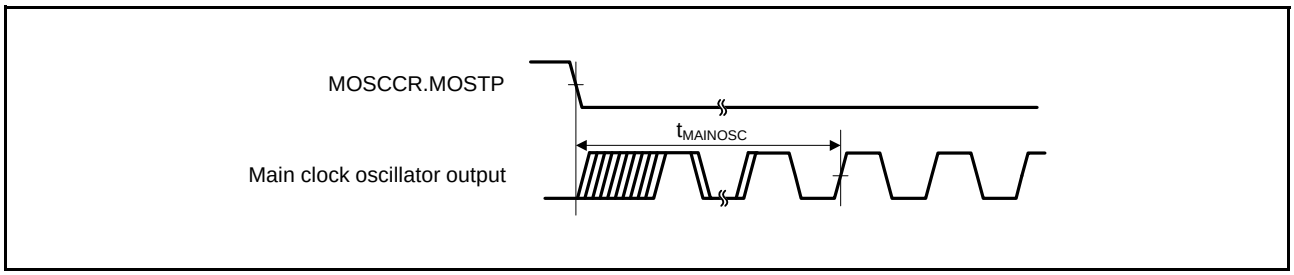


Figure 5.20 Main Clock Oscillation Start Timing

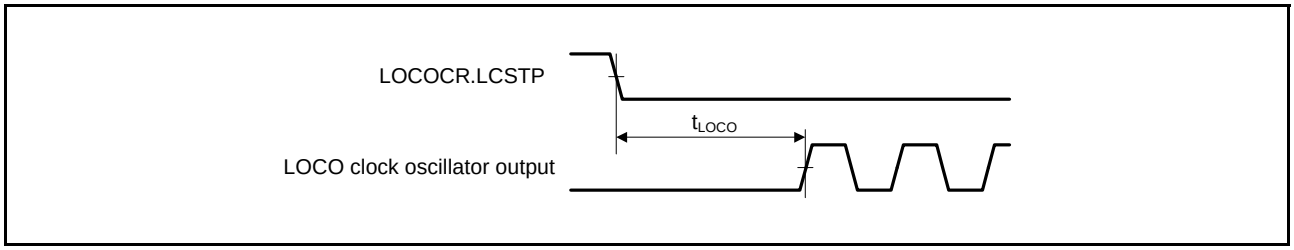


Figure 5.21 LOCO Clock Oscillation Start Timing

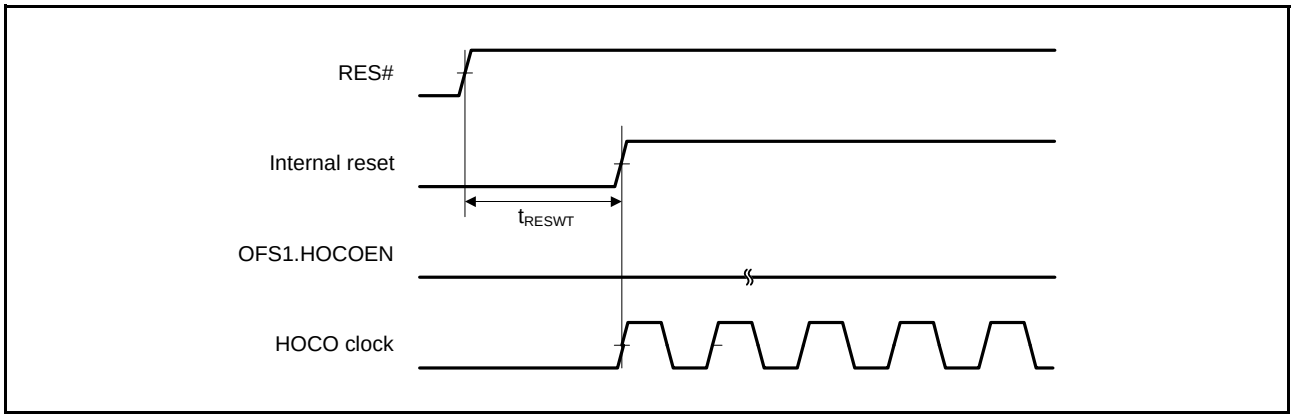


Figure 5.22 HOCO Clock Oscillation Start Timing (After Reset is Canceled by Setting OFS1.HOCOEN Bit to 0)

5.3.3 Timing of Recovery from Low Power Consumption Modes

Table 5.24 Timing of Recovery from Low Power Consumption Modes (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	High-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.28
		External clock input to main clock oscillator	Main clock oscillator operating*3	t_{SBYEX}	—	35	50	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	650	800	µs	
		HOCO clock oscillator operating*4		t_{SBYHO}	—	40	55	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	40	55	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.
Note 2. When the frequency of the crystal is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 3. When the frequency of the external clock is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 4. When the frequency of HOCO is 32 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.25 Timing of Recovery from Low Power Consumption Modes (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Middle-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.28
		External clock input to main clock oscillator	Main clock oscillator operating*3	t_{SBYEX}	—	3	4	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	600	750	µs	
		HOCO clock oscillator operating*4		t_{SBYHO}	—	40	50	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	4.8	7	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.
Note 2. When the frequency of the crystal is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 3. When the frequency of the external clock is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 4. When the frequency of HOCO is 8 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.32 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.39
	SCK clock cycle input (slave)			6	65536		
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.40, Figure 5.42
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SS input setup time		t_{LEAD}	3	—	t_{Pcyc}	
	SS input hold time		t_{LAG}	3	—	t_{Pcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	85		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SS input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

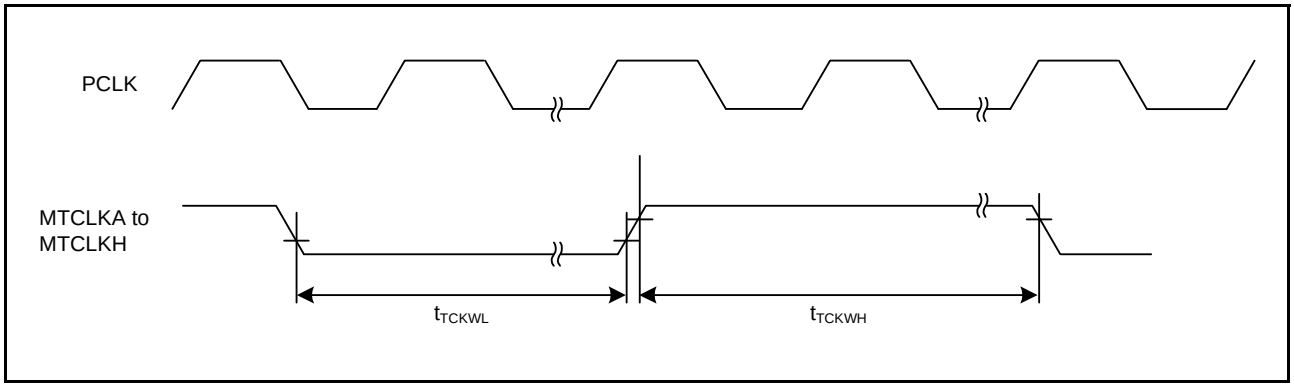


Figure 5.34 MTU2 Clock Input Timing

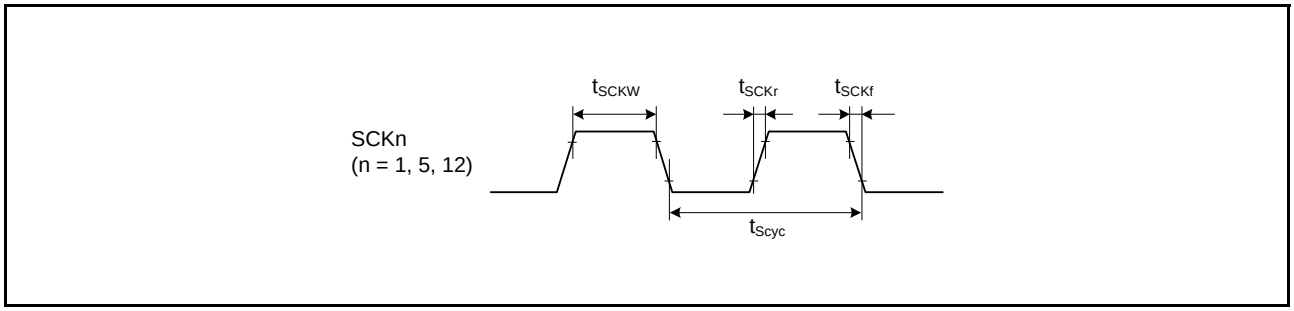


Figure 5.35 SCK Clock Input Timing

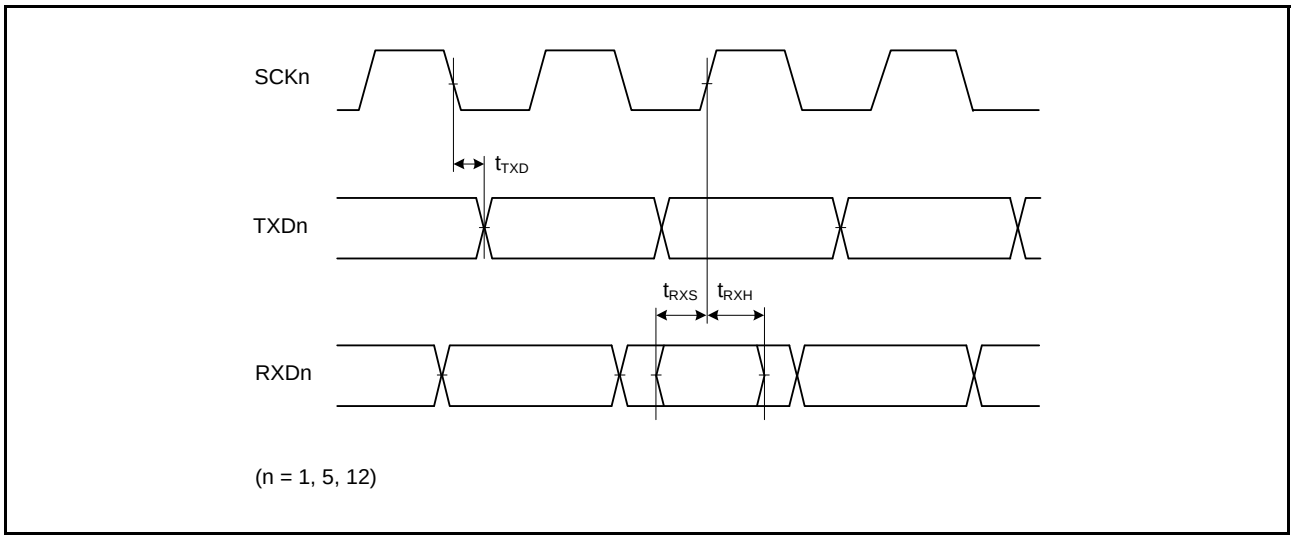


Figure 5.36 SCI Input/Output Timing: Clock Synchronous Mode

5.6 Power-On Reset Circuit and Voltage Detection Circuit Characteristics

Table 5.41 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Power-on reset (POR)	V_{POR}	1.35	1.50	1.65	V	Figure 5.49, Figure 5.50
	Voltage detection circuit (LVD1)*1	V_{det1_4}	3.00	3.10	3.20	V	Figure 5.51 At falling edge VCC
		V_{det1_5}	2.91	3.00	3.09		
		V_{det1_6}	2.81	2.90	2.99		
		V_{det1_7}	2.70	2.79	2.88		
		V_{det1_8}	2.60	2.68	2.76		
		V_{det1_9}	2.50	2.58	2.66		
		V_{det1_A}	2.40	2.48	2.56		
		V_{det1_B}	1.99	2.06	2.13		
		V_{det1_C}	1.90	1.96	2.02		
		V_{det1_D}	1.80	1.86	1.92		

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD2), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet1_n denotes the value of the LVDLVLR.LVD1LVL[3:0] bits.

Table 5.42 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Voltage detection circuit (LVD2)*1	V_{det2_0}	2.71	2.90	3.09	V	Figure 5.52 At falling edge VCC
		V_{det2_1}	2.43	2.60	2.77		
		V_{det2_2}	1.87	2.00	2.13		
		V_{det2_3}*2	1.69	1.80	1.91		
Wait time after power-on reset cancellation	At normal startup*3	t_{POR}	—	9.1	—	ms	Figure 5.50
	During fast startup time*4	t_{POR}	—	1.6	—		
Wait time after voltage monitoring 1 reset cancellation	Power-on voltage monitoring 1 reset disabled*3	t_{LVD1}	—	568	—	µs	Figure 5.51
	Power-on voltage monitoring 1 reset enabled*4		—	100	—		
Wait time after voltage monitoring 2 reset cancellation		t_{LVD2}	—	100	—	µs	Figure 5.52
Response delay time		t_{det}	—	—	350	µs	Figure 5.49
Minimum VCC down time*5		t_{VOFF}	350	—	—	µs	Figure 5.49, VCC = 1.0 V or above
Power-on reset enable time		$t_{W(POR)}$	1	—	—	ms	Figure 5.50, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)		$Td_{(E-A)}$	—	—	300	µs	Figure 5.51, Figure 5.52
Hysteresis width (LVD1 and LVD2)		V_{LVH}	—	70	—	mV	Vdet1_4 selected
			—	60	—		Vdet1_5 to 9, LVD2 selected
			—	50	—		When selection is from among Vdet1_A to B.
			—	40	—		When selection is from among Vdet1_C to D.

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD1), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet2_n denotes the value of the LVDLVLR.LVD2LVL[3:0] bits.

Note 2. Vdet2_3 selection can be used only when the CMPA2 pin input voltage is selected and cannot be used when the power supply voltage (VCC) is selected.

Note 3. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.

Note 4. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.

Note 5. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

5.9 Usage Notes

5.9.1 Connecting VCL Capacitor and Bypass Capacitors

This MCU integrates an internal voltage-down circuit, which is used for lowering the power supply voltage in the internal MCU to adjust automatically to the optimum level. A 4.7-µF capacitor needs to be connected between this internal voltage-down power supply (VCL pin) and VSS pin. Figure 5.54 to Figure 5.55 shows how to connect external capacitors. Place an external capacitor close to the pins. Do not apply the power supply voltage to the VCL pin. Insert a multilayer ceramic capacitor as a bypass capacitor between each pair of the power supply pins. Implement a bypass capacitor to the MCU power supply pins as close as possible. Use a recommended value of 0.1 µF as the capacitance of the capacitors. For the capacitors related to crystal oscillation, see section 9, Clock Generation Circuit in the User's Manual: Hardware. For the capacitors related to analog modules, also see section 27, 12-Bit A/D Converter (S12ADb) in the User's Manual: Hardware.
For notes on designing the printed circuit board, see the descriptions of the application note "Hardware Design Guide" (R01AN1411EJ). The latest version can be downloaded from Renesas Electronics Website.

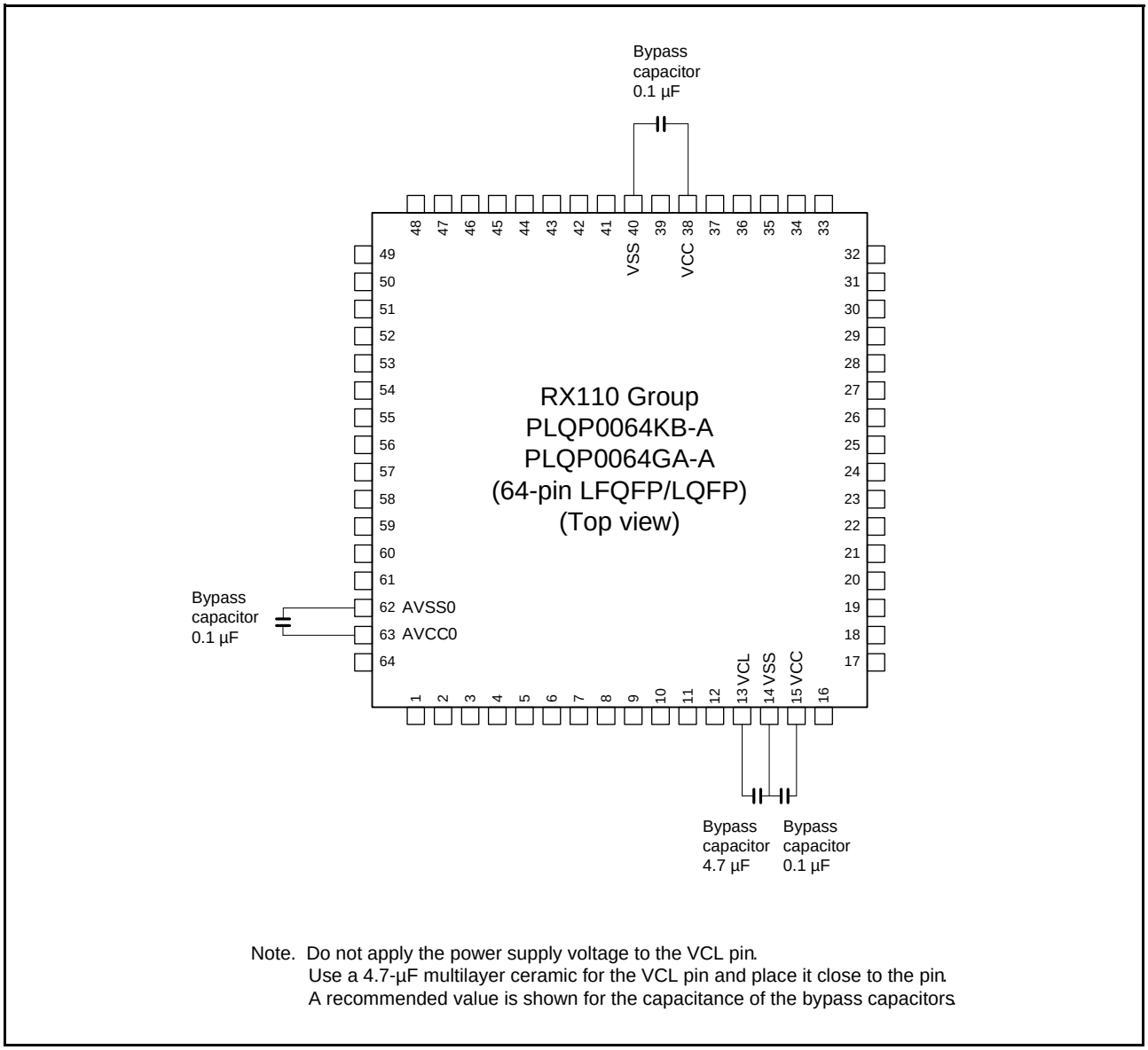
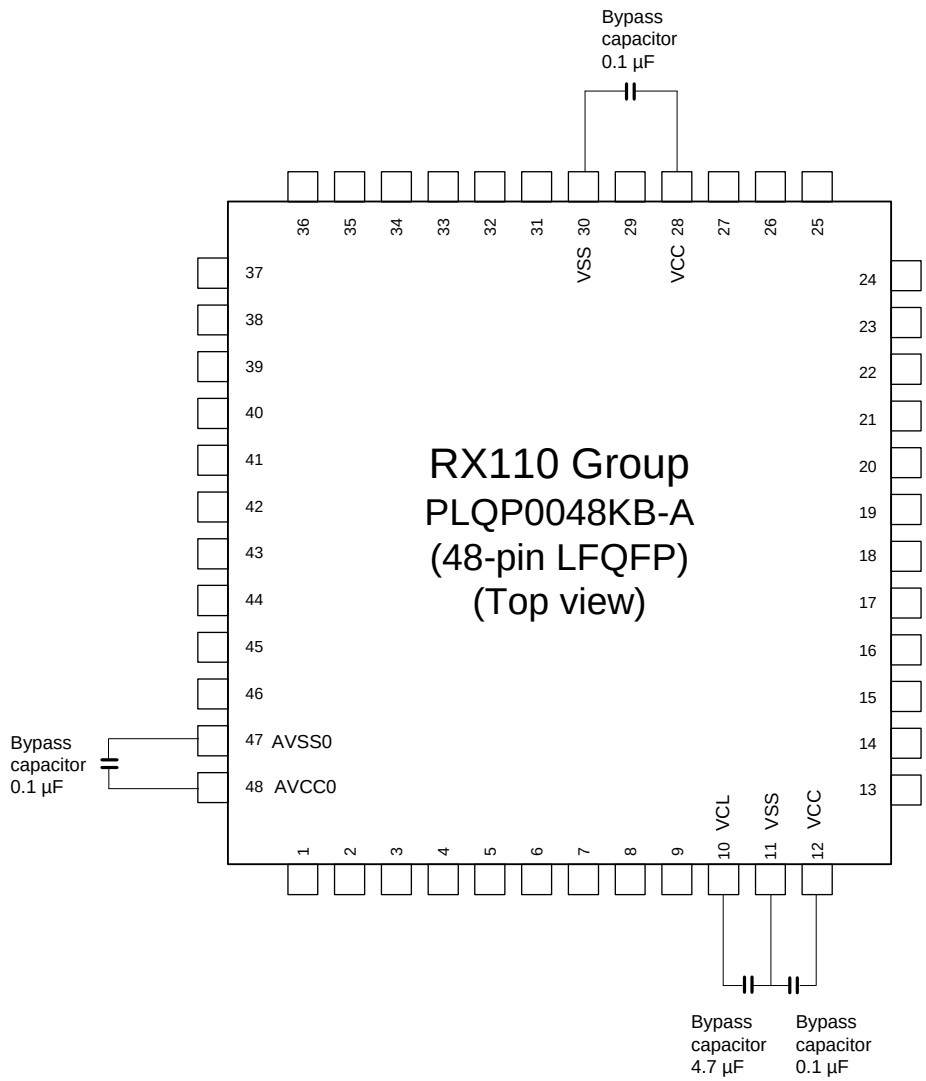


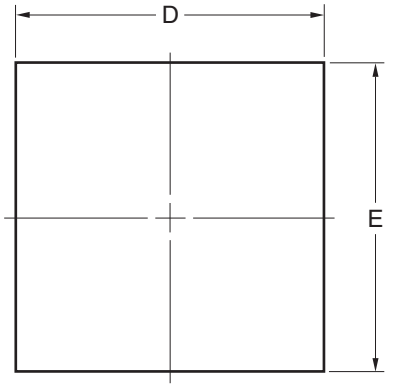
Figure 5.54 Connecting Capacitors (64 Pins)

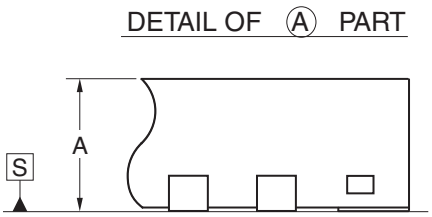


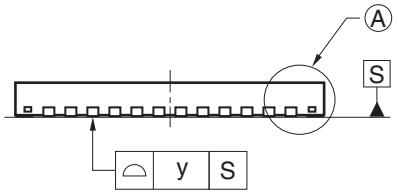
Note. Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

Figure 5.55 Connecting Capacitors (48-pin LFQFP)

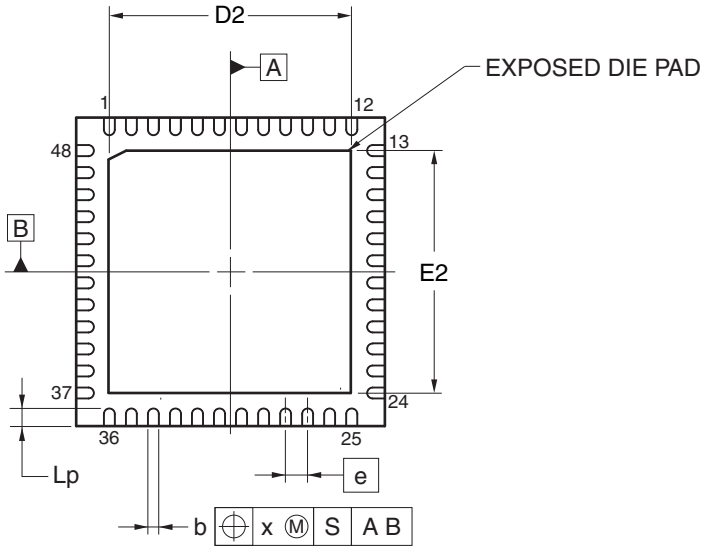
JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PJN-A P48K8-50-5B4-5	0.13







Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.95	7.00	7.05
E	6.95	7.00	7.05
A	0.70	0.75	0.80
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05



ITEM		D2			E2		
		MIN	NOM	MAX	MIN	NOM	MAX
EXPOSED DIE PAD VARIATIONS	A	5.45	5.50	5.55	5.45	5.50	5.55

Figure E 48-Pin HWQFN (PWQN0048KB-A)

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
3. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from such alteration, modification, copy or otherwise misappropriation of Renesas Electronics product.
5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
   "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots etc.
   "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; and safety equipment etc.
   Renesas Electronics products are neither intended nor authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems, surgical implantations etc.), or may cause serious property damages (nuclear reactor control systems, military equipment etc.). You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application for which it is not intended. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for which the product is not intended by Renesas Electronics.
6. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
7. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or systems manufactured by you.
8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
9. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You should not use Renesas Electronics products or technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. When exporting the Renesas Electronics products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations.
10. It is the responsibility of the buyer or distributor of Renesas Electronics products, who distributes, disposes of, or otherwise places the product with a third party, to notify such third party in advance of the contents and conditions set forth in this document, Renesas Electronics assumes no responsibility for any losses incurred by you or third parties as a result of unauthorized use of Renesas Electronics products.
11. This document may not be reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

RENESAS

SALES OFFICES Renesas Electronics Corporation http://www.renesas.com

Refer to "http://www.renesas.com/" for the latest and detailed information.

Renesas Electronics America Inc.
2801 Scott Boulevard Santa Clara, CA 95050-2549, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3
Tel: +1-905-237-2004

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
Room 1709, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100191, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, P. R. China 200333
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited
Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2265-6688, Fax: +852 2886-9022

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.
Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics India Pvt. Ltd.
No.777C, 100 Feet Road, HAL II Stage, Indiranagar, Bangalore, India
Tel: +91-80-67208700, Fax: +91-80-67208777

Renesas Electronics Korea Co., Ltd.
12F., 234 Teheran-ro, Gangnam-Gu, Seoul, 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141

Colophon 5.0